

## 3.3-V PHASE-LOCK LOOP CLOCK DRIVER WITH POWER DOWN MODE

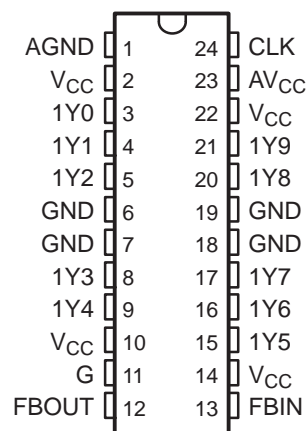
### FEATURES

- Designed to Meet and Exceed PC133 SDRAM Registered DIMM Specification Rev. 1.1
- Spread Spectrum Clock Compatible
- Operating Frequency 20 MHz to 175 MHz
- Static Phase Error Distribution at 66 MHz to 166 MHz is  $\pm 125$  ps
- Jitter (cyc–cyc) at 66 MHz to 166 MHz is  $|70|$  ps
- Advanced Deep Submicron Process Results in More Than 40% Lower Power Consumption vs Current Generation PC133 Devices
- Auto Frequency Detection to Disable Device (Power-Down Mode)
- Available in Plastic 24-Pin TSSOP
- Distributes One Clock Input to One Bank of 10 Outputs
- External Feedback (FBIN) Terminal is Used to Synchronize the Outputs to the Clock Input
- 25- $\Omega$  On-Chip Series Damping Resistors
- No External RC Network Required
- Operates at 3.3 V

### APPLICATIONS

- DRAM Applications
- PLL Based Clock Distributors
- Non-PLL Clock Buffer

PW PACKAGE  
(TOP VIEW)



### DESCRIPTION

The CDCVF2510A is a high-performance, low-skew, low-jitter, phase-lock loop (PLL) clock driver. The CDCVF2510A uses a phase-lock loop (PLL) to precisely align, in both frequency and phase, the feedback (FBOUT) output to the clock (CLK) input signal. It is specifically designed for use with synchronous DRAMs. The CDCVF2510A operates at a 3.3-V  $V_{CC}$  and also provides integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of 10 outputs provides 10 low-skew, low-jitter copies of CLK. Output signal duty cycles are adjusted to 50%, independent of the duty cycle at CLK. Outputs are enabled or disabled via the control (G) input. When the G input is high, the outputs switch in phase and frequency with CLK; when the G input is low, the outputs are disabled to the logic-low state. The device automatically goes into power-down mode when no input signal ( $< 1$  MHz) is applied to CLK; the outputs go into a low state.

Unlike many products containing PLLs, the CDCVF2510A does not require external RC networks. The loop filter for the PLL is included on-chip, minimizing component count, board space, and cost.

Because it is based on PLL circuitry, the CDCVF2510A requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization time is required following power up and application of a fixed-frequency, a fixed-phase signal at CLK, or following any changes to the PLL reference or feedback signals. The PLL can be bypassed by strapping  $AV_{CC}$  to ground to use as a simple clock buffer.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## DESCRIPTION CONTINUED

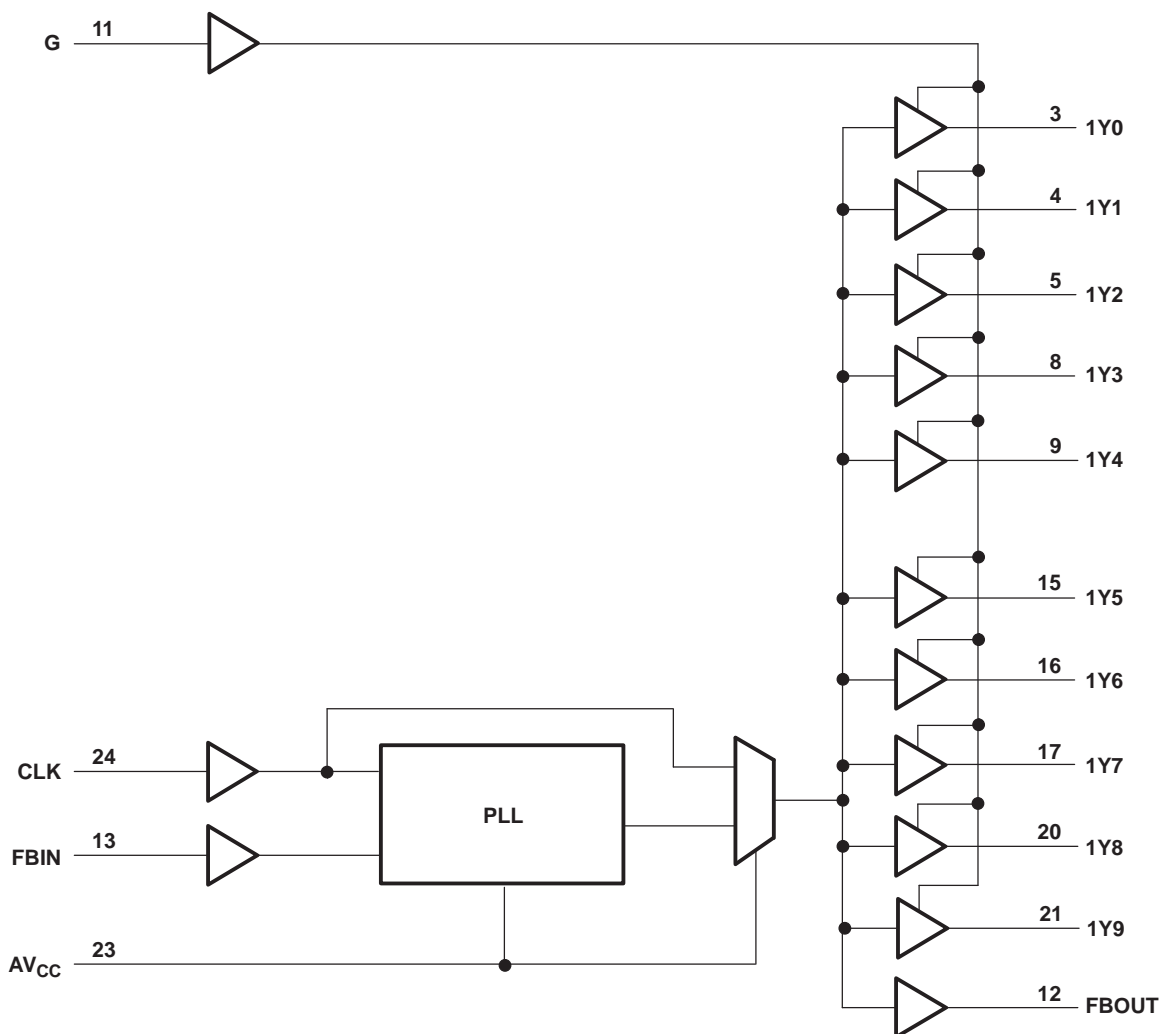
The CDCVF2510A is characterized for operation from 0°C to 85°C.

For application information see the application reports *High Speed Distribution Design Techniques for CDC509/516/2509/2510/2516* (literature number [SLMA003](#)) and *Using CDC2509A/2510A PLL With Spread Spectrum Clocking (SSC)* (literature number [SCAA039](#)).

**FUNCTION TABLE**

INPUTS			OUTPUTS		PLL
AVDD	G	CLK	1Y(0:9)	FBOUT	
GND	L	Signal	L	Signal (delayed)	Bypassed / Off
GND	H	Signal	Signal (delayed)	Signal (delayed)	Bypassed / Off
3.3 V (nom)	L	CLK > 1 MHz	L	CLK (in phase)	On
3.3 V (nom)	H	CLK > 1 MHz	CLK (in phase)	CLK (in phase)	On
3.3 V (nom)	X	CLK < 1 MHz	L	L	Off

## FUNCTIONAL BLOCK DIAGRAM



## AVAILABLE OPTIONS

T <sub>A</sub>	PACKAGE
	SMALL OUTLINE (PW)
0°C to 85°C	CDCVF2510APWR
	CDCVF2510APW

### Terminal Functions

TERMINAL NAME	NO.	TYPE	DESCRIPTION
CLK	24	I	Clock input. CLK provides the clock signal to be distributed by the CDCVF2510A clock driver. CLK is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLK must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid CLK signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to its reference signal.
FBIN	13	I	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be hard-wired to FBOUT to complete the PLL. The integrated PLL synchronizes CLK and FBIN so that there is nominally zero phase error between CLK and FBIN.
G	11	I	Output bank enable. G is the output enable for outputs 1Y(0:9). When G is low, outputs 1Y(0:9) are disabled to a logic-low state. When G is high, all outputs 1Y(0:9) are enabled and switch at the same frequency as CLK.
FBOUT	12	O	Feedback output. FBOUT is dedicated for external feedback. It switches at the same frequency as CLK. When externally wired to FBIN, FBOUT completes the feedback loop of the PLL. FBOUT has an integrated 25-Ω series-damping resistor.
1Y (0:9)	3, 4, 5, 8, 9, 15, 16, 17, 20, 21	O	Clock outputs. These outputs provide low-skew copies of CLK. Output bank 1Y(0:9) is enabled via the G input. These outputs can be disabled to a logic-low state by deasserting the G control input. Each output has an integrated 25-Ω series-damping resistor.
AV <sub>CC</sub>	23	Power	Analog power supply. AV <sub>CC</sub> provides the power reference for the analog circuitry. In addition, AV <sub>CC</sub> can be used to bypass the PLL. When AV <sub>CC</sub> is strapped to ground, PLL is bypassed and CLK is buffered directly to the device outputs.
AGND	1	Ground	Analog ground. AGND provides the ground reference for the analog circuitry.
V <sub>CC</sub>	2, 10, 14, 22	Power	Power supply
GND	6, 7, 18, 19	Ground	Ground

### ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)

AV <sub>CC</sub>	Supply voltage range <sup>(1)</sup>	AV <sub>CC</sub> < V <sub>CC</sub> + 0.7 V
V <sub>CC</sub>	Supply voltage range	-0.5 V to 4.3 V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5 V to 4.6 V
V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	-0.5 V to V <sub>CC</sub> + 0.5 V
I <sub>IK</sub>	Input clamp current, (V <sub>I</sub> < 0)	-50 mA
I <sub>OK</sub>	Output clamp current, (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
I <sub>O</sub>	Continuous output current, (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±50 mA
	Continuous current through each V <sub>CC</sub> or GND	±100 mA
Z <sub>θJA</sub>	Junction-to-ambient package thermal impedance <sup>(4)</sup>	114.5°C/W
Z <sub>θJC</sub>	Junction-to-case thermal impedance <sup>(4)</sup>	25.7°C/W
T <sub>J</sub>	Maximum allowable junction temperature	125°C
T <sub>stg</sub>	Storage temperature range	-65°C to 150°C

(1) AV<sub>CC</sub> must not exceed V<sub>CC</sub> + 0.7 V.

(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance and junction-to-case thermal impedance are calculated in accordance with JESD51 (no air flow condition) and JEDEC252P (high-k board).

## RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}, AV_{CC}$	Supply voltage	3	3.6	V
$V_{IH}$	High-level input voltage	2		V
$V_{IL}$	Low-level input voltage		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current		–12	mA
$I_{OL}$	Low-level output current,		12	mA
$f_{clk}$	Clock frequency <sup>(2)</sup>	20	175	MHz
	Input clock duty cycle	40%	60%	
	Stabilization time		1	ms

(1) Unused inputs must be held high or low to prevent them from floating.

(2) Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the *switching characteristics* table are not applicable. This parameter does not apply for input modulation under SSC application.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}, AV_{CC}$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$V_{IK}$	Input clamp voltage	$I_I = -18$ mA	3 V		–1.2	V
$V_{OH}$	High-level output voltage	$I_{OH} = -100$ $\mu$ A	MIN to MAX	$V_{CC}-0.2$		V
		$I_{OH} = -12$ mA	3 V	2.1		
		$I_{OH} = -6$ mA	3 V	2.4		
$V_{OL}$	Low-level output voltage	$I_{OL} = 100$ $\mu$ A	MIN to MAX		0.2	V
		$I_{OL} = 12$ mA	3 V		0.8	
		$I_{OL} = 6$ mA	3 V		0.55	
$I_{OH}$	High-level output current	$V_O = 1$ V	3 V	–28		mA
		$V_O = 1.65$ V	3.3 V	–36		
		$V_O = 3.135$ V	3.6 V		–8	
$I_{OL}$	Low-level output current	$V_O = 1.95$ V	3 V	30		mA
		$V_O = 1.65$ V	3.3 V		40	
		$V_O = 0.4$ V	3.6 V		10	
$I_I$	Input current	$V_I = V_{CC}$ or GND	3.6 V		$\pm 5$	$\mu$ A
$I_{CC}$ <sup>(2)</sup>	Supply current (static, output not switching)	$V_I = V_{CC}$ or GND, $I_O = 0$ , Outputs: low or high	3.6 V, 0 V		40	$\mu$ A
$\Delta I_{CC}$	Change in supply current	One input at $V_{CC} - 0.6$ V, Other inputs at $V_{CC}$ or GND	3.3 V to 3.6 V		500	$\mu$ A
$C_i$	Input capacitance	$V_I = V_{CC}$ or GND	3.3 V		2.5	pF
$C_o$	Output capacitance	$V_O = V_{CC}$ or GND	3.3 V		2.8	pF

(1) For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

(2) For dynamic  $I_{CC}$  vs Frequency, see [Figure 9](#) and [Figure 10](#).

## SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 25$  pF (see Note <sup>(1)</sup> and Figure 1 and Figure 2)<sup>(2)</sup>

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}, AV_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			UNIT
			MIN	TYP	MAX	
$t_{\phi}$ Phase error time-static (normalized) (see Figure 4 through Figure 7)	CLK↑ = 25 MHz to 65 MHz	FBIN↑	-150		150	ps
	CLK↑ = 66 MHz to 175 MHz		-125		125	
$t_{sk(o)}$ Output skew time <sup>(3)</sup>	Any Y	Any Y			100	ps
Phase error time-jitter <sup>(4)</sup>	CLK = 66 MHz to 175 MHz	Any Y or FBOUT	-50		50	ps
Jitter <sub>(cycle-cycle)</sub> (see Figure 8)	CLK = 25 MHz to 40 MHz	Any Y or FBOUT			500	ps
	CLK = 41 MHz to 59 MHz				200	
	CLK = 60 MHz to 175 MHz			65	125	
$t_{d(\phi)}$ Dynamic phase offset <sup>(5)</sup>	CLK↑ = 25 MHz to 65 MHz	FBIN↑			1.5	ns
	CLK↑ = 66 MHz to 175 MHz				0.4	
Duty cycle	$f_{(CLK)} > 60$ MHz	Any Y or FBOUT	45%		55%	
$t_r$ Rise time	$V_O = 0.4\text{ V}$ to $2\text{ V}$	Any Y or FBOUT	0.3		1.1	ns/V
$t_f$ Fall time	$V_O = 2\text{ V}$ to $0.4\text{ V}$	Any Y or FBOUT	0.3		1.1	ns/V
$t_{PLH}$ Low-to-high propagation delay time, bypass mode	CLK	Any Y or FBOUT	1.8		3.9	ns
$t_{PHL}$ High-to-low propagation delay time, bypass mode	CLK	Any Y or FBOUT	1.8		3.9	ns

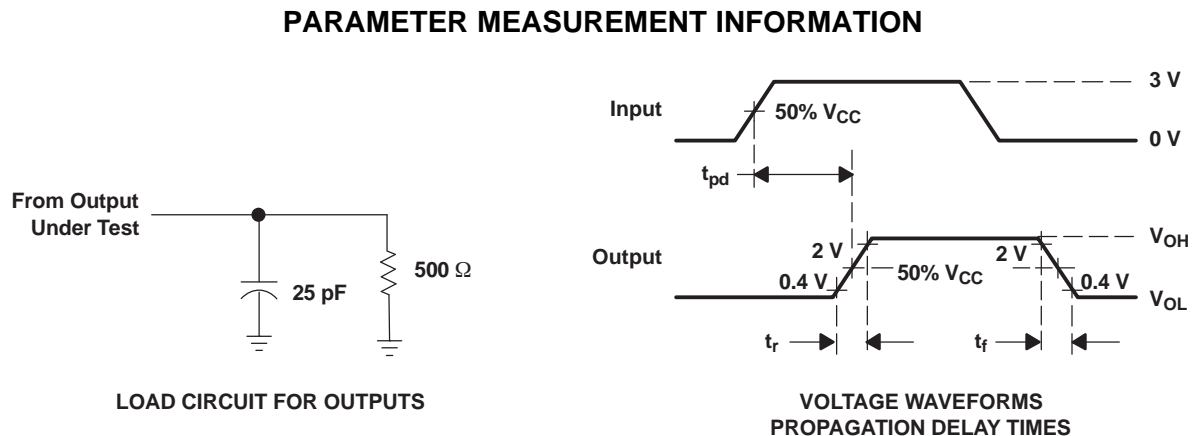
(1) The specifications for parameters in this table are applicable only after any appropriate stabilization time has elapsed.

(2) These parameters are not production tested.

(3) The  $t_{sk(o)}$  specification is only valid for equal loading of all outputs.

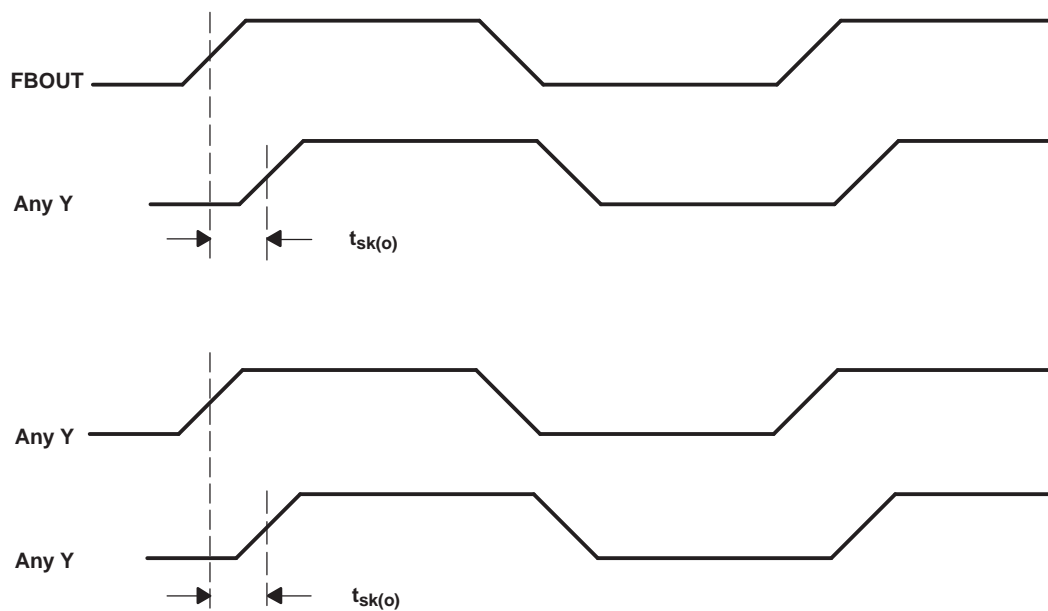
(4) Calculated per PC DRAM SPEC ( $t_{\text{phase error, static}} - \text{jitter}_{(\text{cycle-to-cycle})}$ ).

(5) The parameter is assured by design but cannot be 100% production tested.

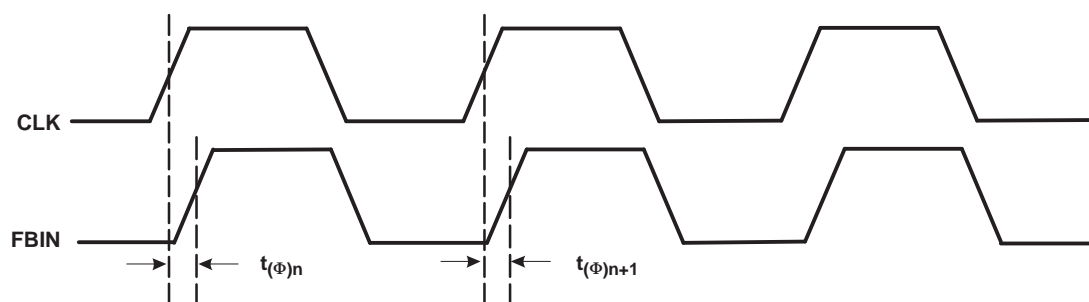


- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 133$  MHz,  $Z_O = 50\ \Omega$ ,  $t_r \leq 1.2$  ns,  $t_f \leq 1.2$  ns.  
 C. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

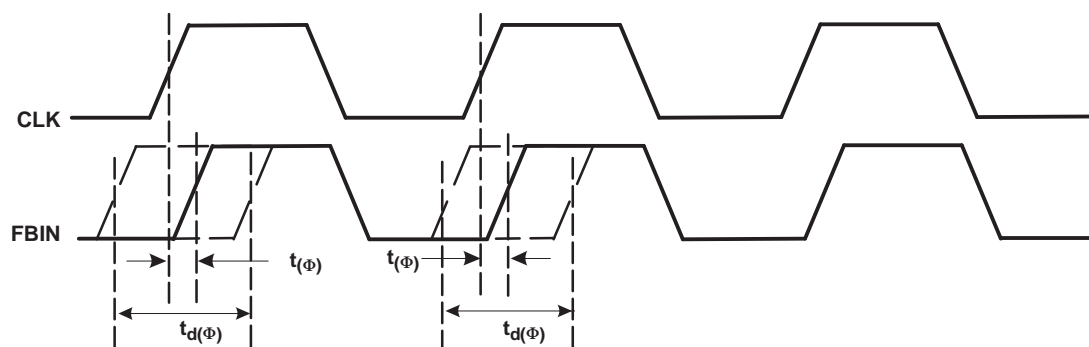


**Figure 2. Skew Calculations**



$$t_{(\Phi)} = \frac{\sum_{n=1}^{n=N} t_{(\Phi)n}}{N} \quad (N \text{ is a large number of samples})$$

a) Static Phase Offset



b) Dynamic Phase Offset

**Figure 3. Static and Dynamic Phase Offset**



## TYPICAL CHARACTERISTICS

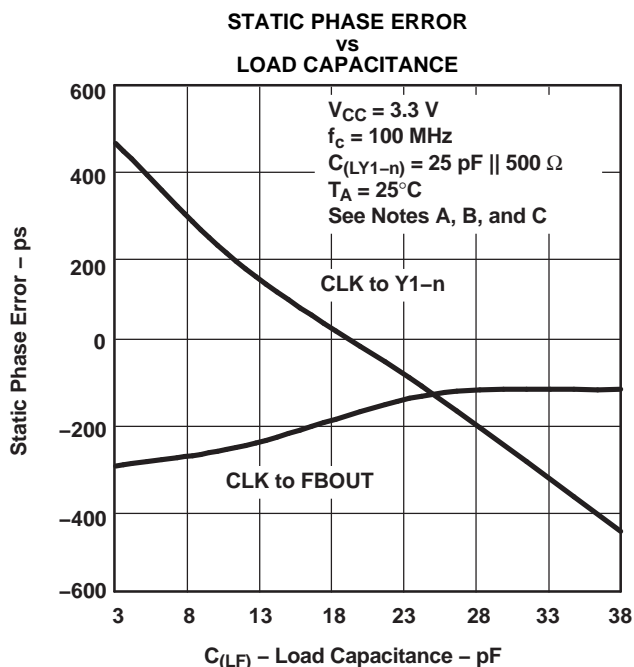


Figure 4.

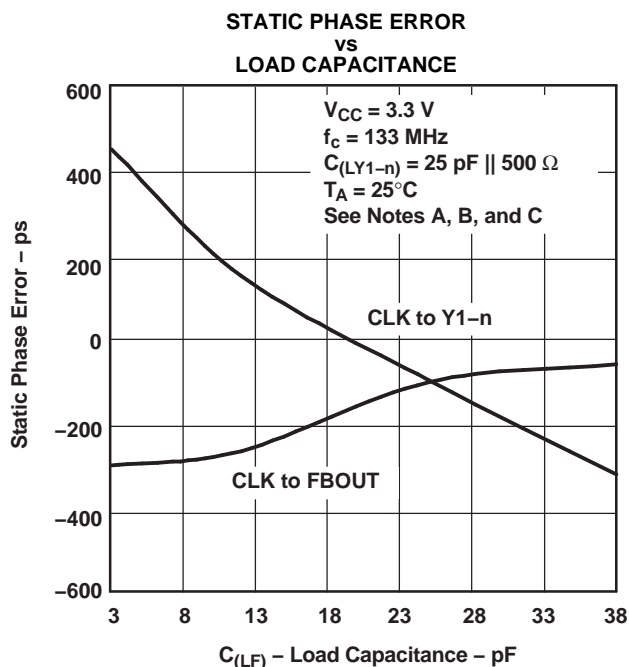


Figure 5.

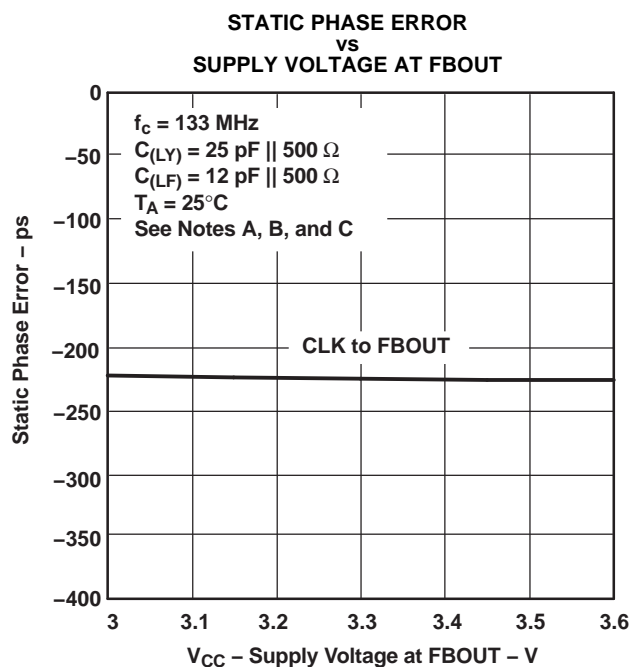


Figure 6.

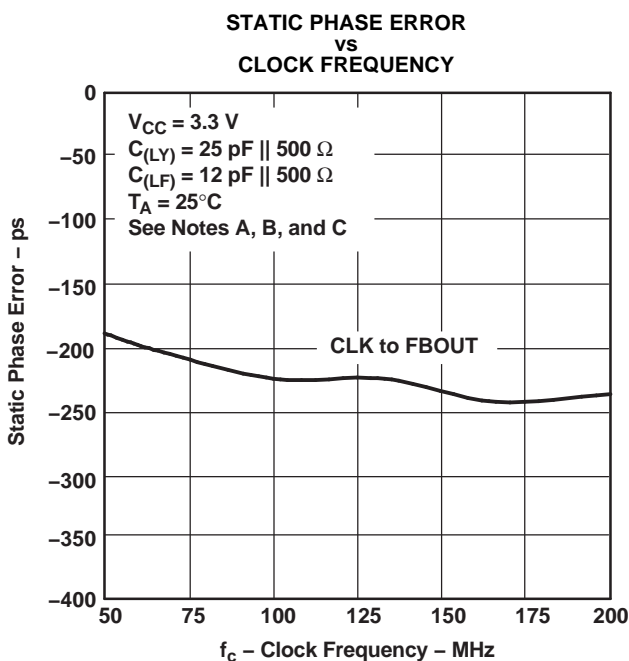


Figure 7.

- A. Trace length FBOUT to FBIN = 5 mm,  $Z_0 = 50 \Omega$
- B.  $C_{(LY)}$  = Lumped capacitive load  $Y_{1-n}$
- C.  $C_{(LFx)}$  = Lumped feedback capacitance at FBOUT = FBIN

## TYPICAL CHARACTERISTICS (continued)

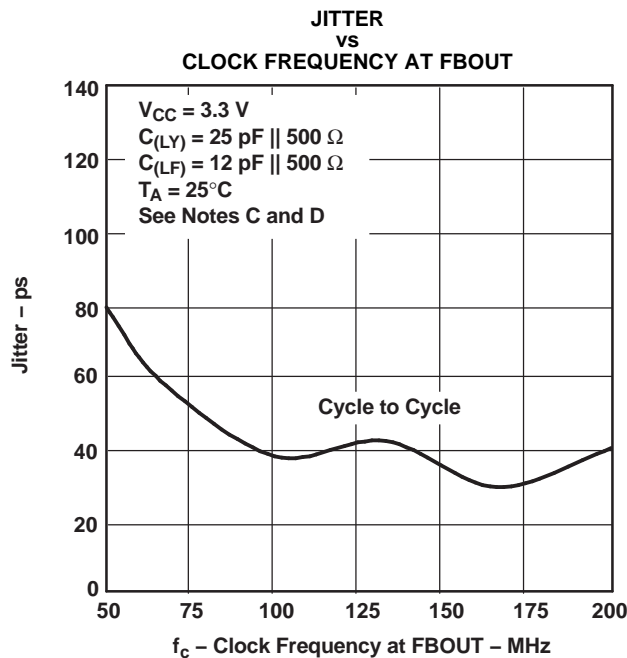


Figure 8.

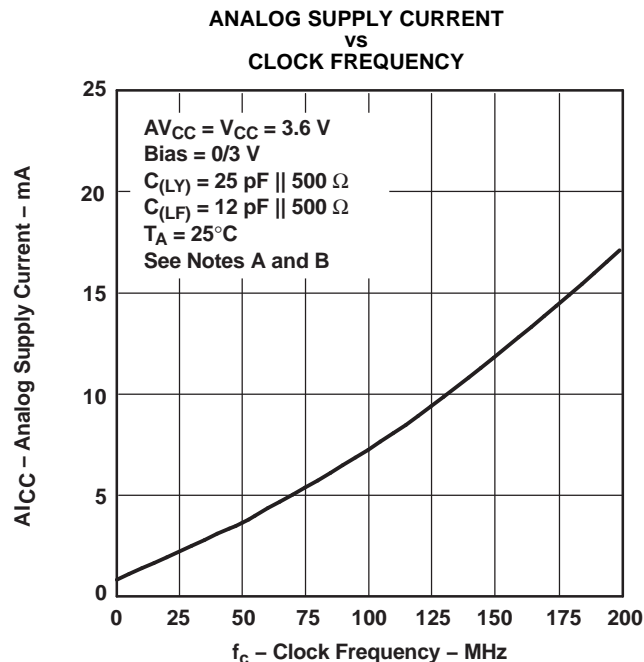


Figure 9.

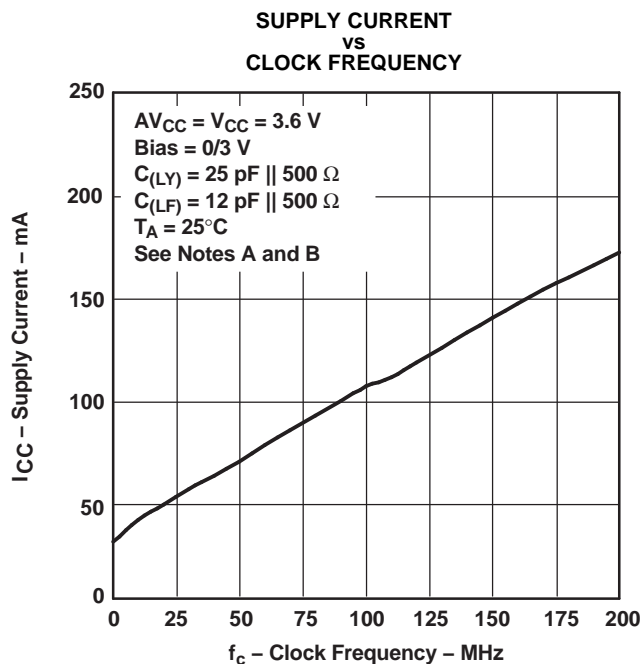


Figure 10.

- A. Trace length FBOUT to FBIN = 5 mm,  $Z_0 = 50 \Omega$
- B.  $C_{(LY)}$  = Lumped capacitive load  $Y_{1-n}$
- C.  $C_{(LFx)}$  = Lumped feedback capacitance at FBOUT = FBIN
- D.  $C_{(LFx)}$  = Lumped feedback capacitance at FBOUT = FBIN

## Revision History

**Table 1. Revision History**

Date	Rev	Page	Section	Description
04/11/05	B	6	Switching Characteristics	Added static phase error - 25 MHz to 65 MHz
				Added jitter - 25 MHz to 65 MHz
				Added Dynamic Phase Offset specification
		7	<a href="#">Figure 2</a>	Revised into two figures
		8	<a href="#">Figure 3</a>	Added Figure 3 for a diagram of dynamic phase offset
2/09/09	C	2	Function Table	Revised for clarity

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CDCVF2510APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDCVF2510APWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDCVF2510APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDCVF2510APWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCVF2510APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS

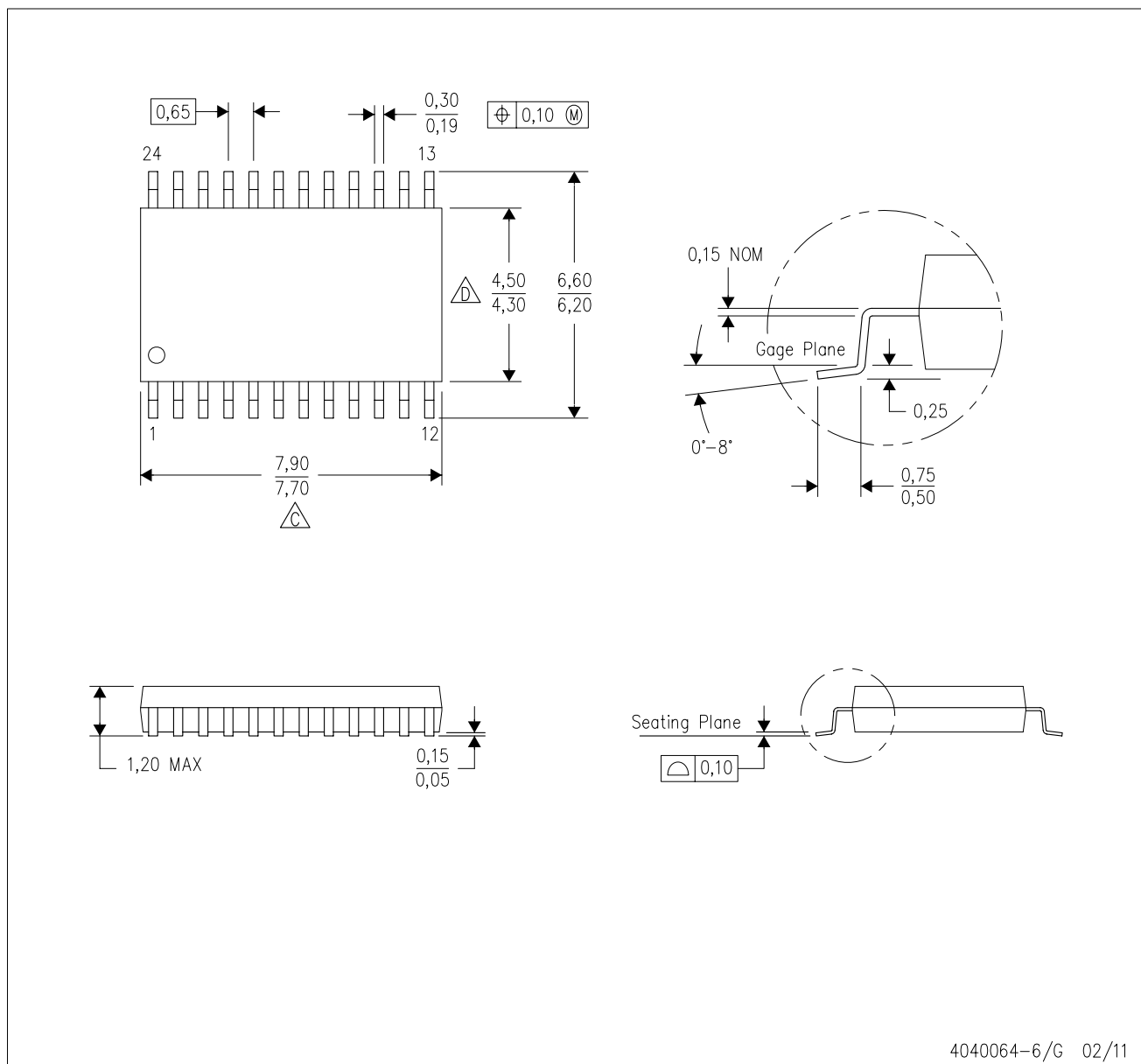


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCVF2510APWR	TSSOP	PW	24	2000	367.0	367.0	38.0

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

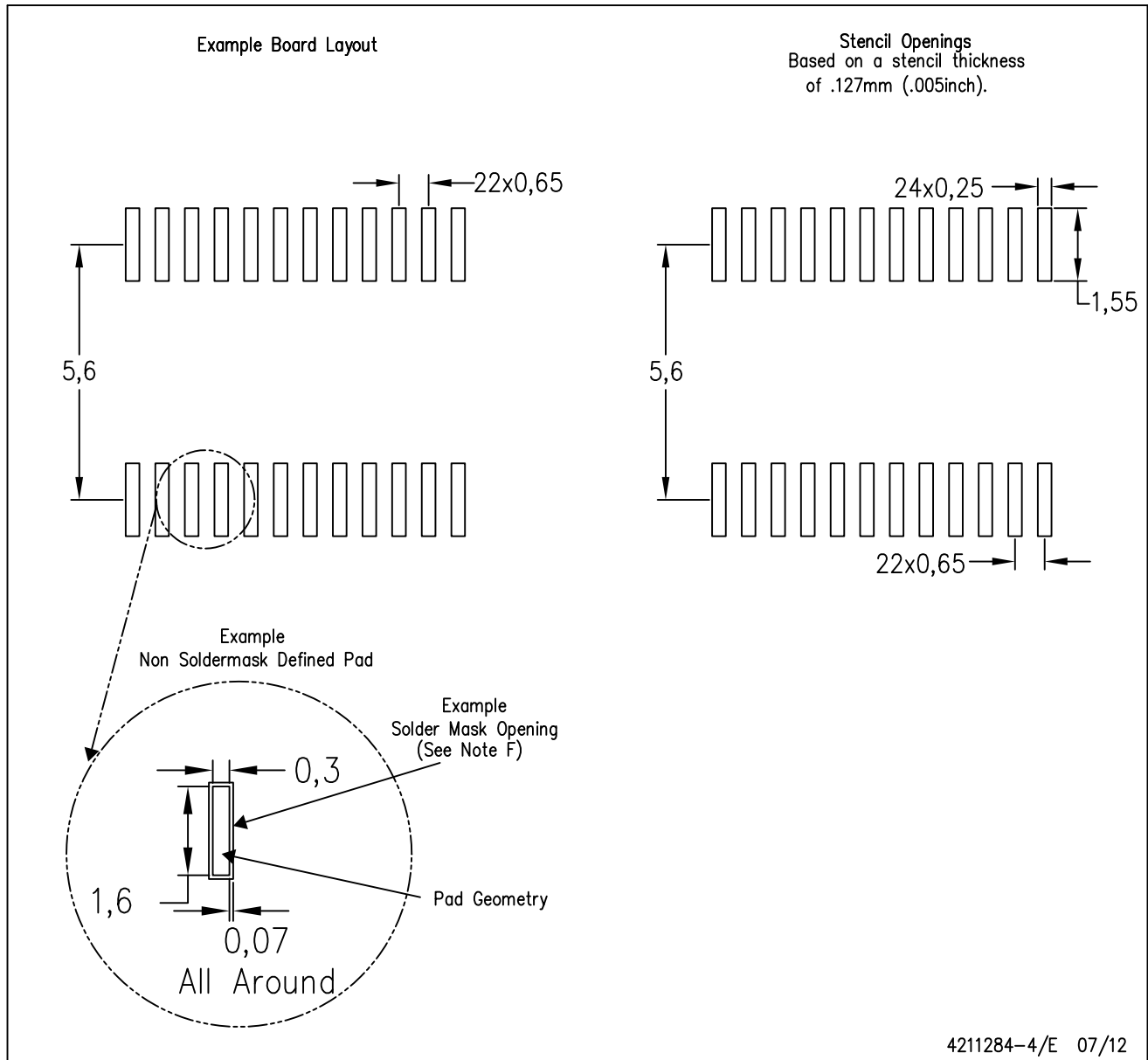


4040064-6/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Mobile Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)